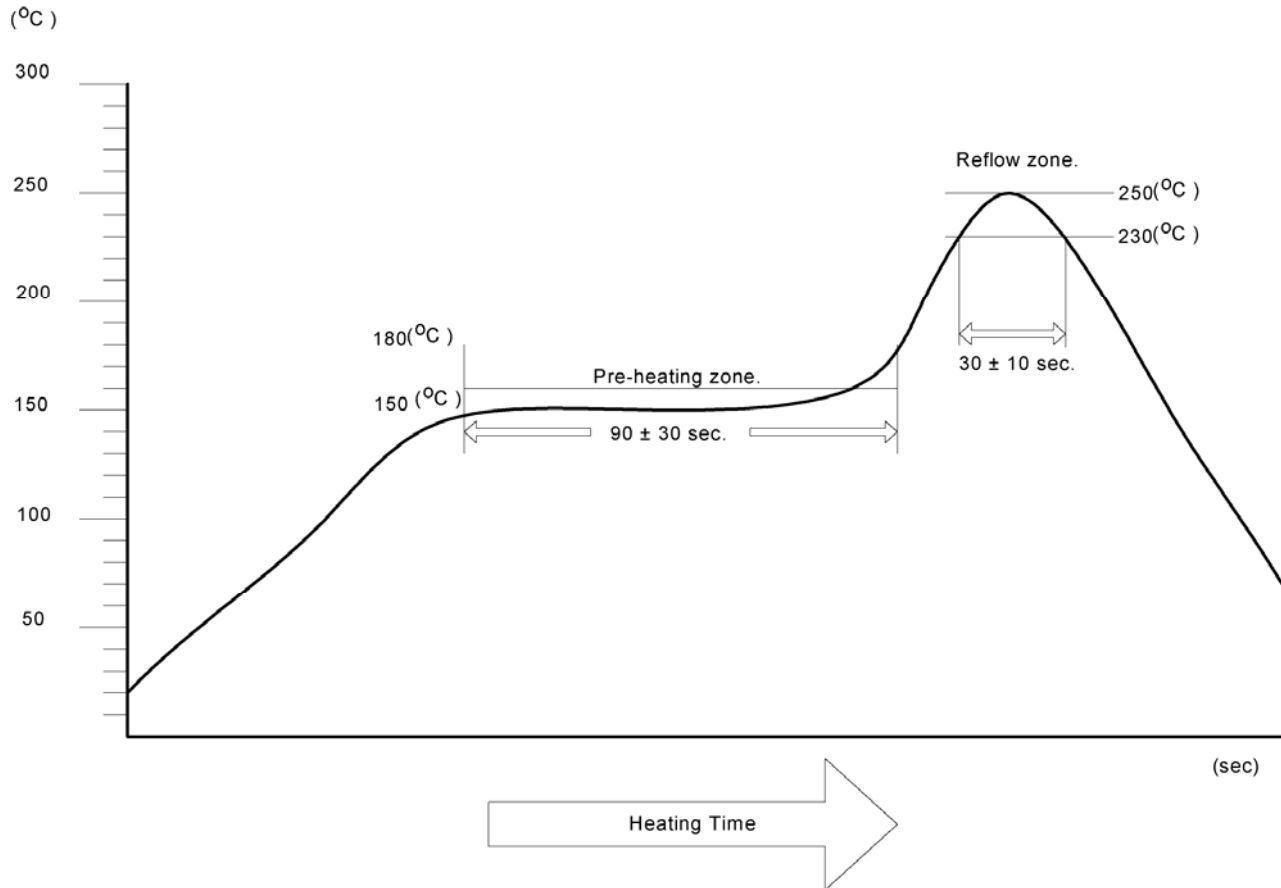


Solder Reflow Profile for PB-Free Process



Profile assumes Sn (96.5) Ag (3.0-3.5) Cu (0.0-0.5) type reduced silver alloy for VCO/PLL attachment.

1) Pre-heating Zone:

Time within 150-180°C = 90 ± 30 sec.

2) Reflow Zone:

Time above 230°C = 30 ± 10 sec. Max = 250°C ± 5°C.

3) Max surface temperature of component is not to exceed 260°C.